

CLAIMS:

1. A semiconductor encapsulating epoxy resin composition comprising

- 5 (A) an epoxy resin,
(B) a phenolic resin curing agent,
(C) a molybdenum compound, and
(D) 300 to 900 parts by weight per 100 parts by weight
of components (A) and (B) combined of an inorganic filler,
10 wherein nitrogen atoms are contained in component (A) and/or
component (B) in an amount of 1.5 to 20% by weight based on
the weight of components (A) and (B) combined.

2. The epoxy resin composition of claim 1 wherein
15 component (B) is a phenolic resin containing nitrogen atoms
in its skeleton in the form of a triazine ring structure,
guanamine skelton or cyanurate skelton.

3. The epoxy resin composition of claim 1 wherein
20 component (A) is an epoxy resin containing nitrogen atoms in
its skeleton in the form of a triazine ring structure,
guanamine skelton or cyanurate skelton.

4. The epoxy resin composition of claim 1 wherein the
25 molybdenum compound (C) is zinc molybdate.

5. The epoxy resin composition of claim 2 wherein the
molybdenum compound (C) is zinc molybdate supported on an
inorganic filler.

6. A semiconductor device encapsulated with a cured
30 product of the epoxy resin composition of claim 1.